Hojyo does not teach or suggest this feature either alone or in the combination as claimed. In this way, for example, a semiconductor die can be disposed on the die mount and, due to the recess, still have its top surface coplanar with of even below the leadframe leads to allow easy connection between die pads on the die and leadframe leads.

Claim 6 contains the features discussed above with reference to claim 1 and therefore defines over Hojyo for at least the reasons set forth above with reference to claim 1.

Claim 6 further requires a semiconductor die mounted in the recess. No such feature is taught or suggested by Hojyo either alone or in the combination as claimed.

Claim 7 depends from claim 6 and therefore defines patentably over Hojyo for at least the reasons presented above with reference to claim 6.

Claim 7 further limits claim 6 by requiring that the stabilizer be made of an insulating material. No such combination is taught or suggested by Hojyo.

Claim 10 relates to a method and requires the step of providing a stabilizer having a die pad integral therewith and disposed beneath the central semiconductor die-receiving region. No such step is taught or suggested by Hojyo either alone or in the combination as claimed.

Claim 11 and 12 depend from claim 10 and therefore define over Hojyo for at least the reasons presented above with reference to claim 10.

In addition, claim 11 further limits claim 10 by requiring the step of forming a recessed area in the die pad for mounting of a semiconductor die therein. No such step is taught or suggested by Hojyo either alone or in the combination as claimed.

Claim 12 further limits claim 10 by requiring that the stabilizer be made of an insulating material. No such combination is taught or suggested by Hojyo.

In view of the above remarks, favorable reconsideration and allowance are respectfully requested.

Respectfully submitted,

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